

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chen-Hua YU</td> <td>06/11/2012</td> </tr> <tr> <td>Ming-Ji LII</td> <td>06/11/2012</td> </tr> <tr> <td>Chung-Shi LIU</td> <td>06/11/2012</td> </tr> <tr> <td>Meng-Tse CHEN</td> <td>06/11/2012</td> </tr> <tr> <td>Wei-Hung LIN</td> <td>06/11/2012</td> </tr> <tr> <td>Ming-Da CHENG</td> <td>06/11/2012</td> </tr> </tbody> </table>		Name	Execution Date	Chen-Hua YU	06/11/2012	Ming-Ji LII	06/11/2012	Chung-Shi LIU	06/11/2012	Meng-Tse CHEN	06/11/2012	Wei-Hung LIN	06/11/2012	Ming-Da CHENG	06/11/2012
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI, Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300				
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PROPERTY NUMBERS Total: 1															
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Application Number:	13526073														
CORRESPONDENCE DATA															
Fax Number:	(703)518-5499														
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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.															
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OP \$40.00 13526073

NAME OF SUBMITTER:

Randy A. Noranbrock

Total Attachments: 2

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|------------------|------------------|
| 1) Chen-Hua YU | 4) Meng-Tse CHEN |
| 2) Mirng-Ji LIH | 5) Wei-Hung LIN |
| 3) Chung-Shi LIU | 6) Ming-Da CHENG |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled


PACKAGE ON PACKAGE STRUCTURES AND MEHTHODS FOR FORMING THE SAME


- (a) for which an application for United States Letters Patent was filed on 2012-06-18, and identified by United States Patent Application No. 13/526,073; or
- (b) for which an application for United States Letters Patent was executed on _____,

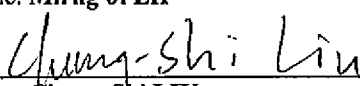
and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

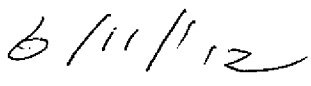
AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

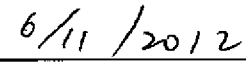
SIGNED on the date indicated aside my signature:

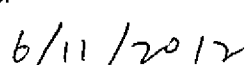
1) 
Name: Chen-Hua YU

2) 
Name: Mirng-Ji LIH

3) 
Name: Chung-Shi LIU


Date: _____


Date: 6/11/2012


Date: 6/11/2012

4) Chen, Meng-Tse
Name: Meng-Tse CHEN

2012/06/11
Date:

5) Wei-Hung Li
Name: Wei-Hung LIN

2012/06/11
Date:

6) Ming-Da cheng
Name: Ming-Da CHENG

2012/06/11
Date: